

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/23/13886	
<b>1.3 Title of PCN</b>	ST Shenzhen (China) TSSOP20 package copper alloy bonding wire introduction on STM32C01x, STM32C03x, STM32G05x and STM32G06x listed products	
<b>1.4 Product Category</b>	STM32C01x STM32C03x STM32G05x STM32G06x	
<b>1.5 Issue date</b>	2023-01-22	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ST Shenzhen (China)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Wire bonding material: - Amkor ATP (Philippines) gold wire	Wire bonding material: - ST Shenzhen (China) copper alloy wire - Amkor ATP (Philippines) gold wire
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	no impact on form, Fit, Function	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	To improve Capacity and flexibility to support customer growing demand.
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Traceability ensured by ST internal tools
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2023-03-28
<b>7.2 Intended start of delivery</b>	2023-04-06
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	13886 MDG-GPM-RER2219 PCN13703 PCN13886 STS TSSOP20 Cu alloy wire intro on STM32C0x-G0x - reliability plan.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2023-01-22

**9. Attachments (additional documentations)**

13886 Public product.pdf  
13886 MDG-GPM-RER2219 PCN13703 PCN13886 STS TSSOP20 Cu alloy wire intro on STM32C0x-G0x - reliability plan.pdf  
13886 PCN13886\_Additional information.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32C011F4P6	
	STM32C011F6P6	
	STM32C031F4P6	
	STM32C031F6P6	



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** ST Shenzhen (China) TSSOP20 package copper alloy bonding wire introduction on STM32C01x, STM32C03x, STM32G05x and STM32G06x listed products

**PCN Reference :** MDG/23/13886

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32C031F6P6	STM32G061F8P6	STM32C011F6P6
STM32C011F6P7TR	STM32C031F4P6	STM32C011F6P7
STM32G050F6P6	STM32G061F6P6	STM32C031F4P6TR
STM32C031F6P7	STM32G051F8P6	STM32C011F6P3TR
STM32C031F6P6TR	STM32G051F6P6	STM32C011F6P3
STM32C011F4P6	STM32C011F6P6TR	STM32C031F6P7TR

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